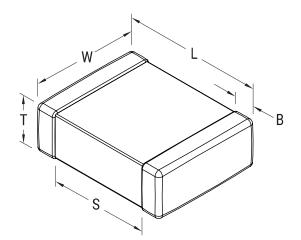




SMD Comm X8G HT150C Flex, Ceramic, 220 pF, 5%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

	Specifications	
1210	Capacitance	220 pF
3.3mm +/-0.4mm	Measurement Condition	1 MHz 1.0Vrms
2.6mm +/-0.3mm	Tolerance	5%
0.78mm +/-0.20mm	Voltage DC	250 VDC
1.5mm MIN	Dielectric Withstanding Voltage	625 VDC
0.6mm +/-0.25mm	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
	Capacitance Change with	30 ppm/C, 1Me
T&R, 330mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
10000		

Chip Size L W т s В

Packaging Specifications Packaging

Dimensions

Packaging Quantity 10000

Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms	
Dissipation Factor	0.1% 1 MHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

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